



**CHAM Limited**

*Pioneering CFD Software for Education & Industry*

## **CHAM Case Study – Flow in a Water-cooled Electronics Box**

**PHOENICS/HOTBOX Demonstration Case using PHOENICS-3.6.2 (2007)**

### **Introduction**

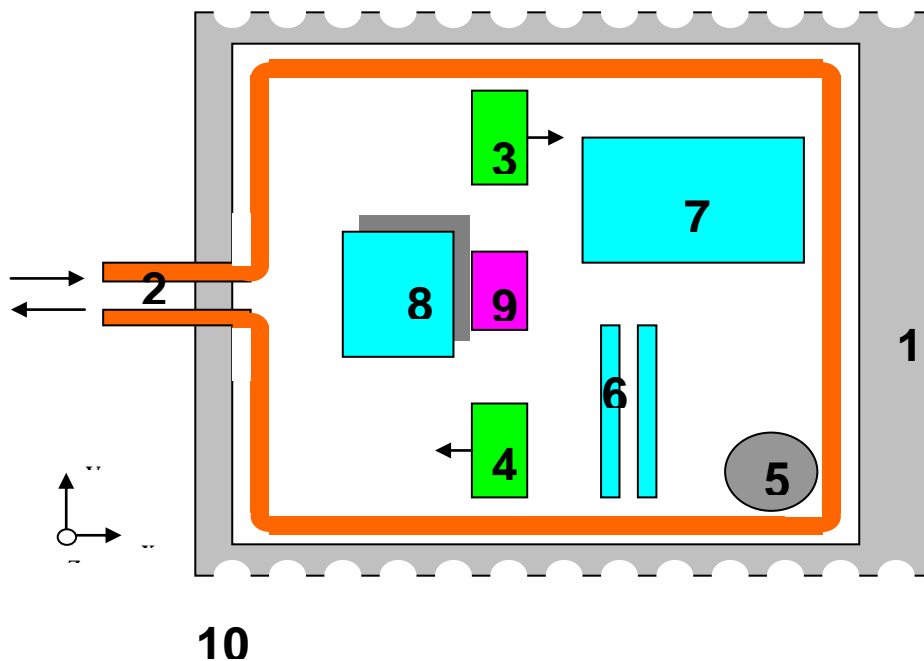
CHAM was approached by Norwegian technology development giant, Kongsberg Devotek AS, and requested to model its prototype design for a water-cooled electronics system housed in a finned aluminium box filled with air at 1 bar.

### **The problem considered**

The pump supplying the water to the cooling system can sometimes break down so that the water remains within the pipes but no longer circulates – or cools. The system fails when one of the boards within the section labeled '8' reaches 75°C. The primary concerns for the customer being “Will the system fail and when? For how long can the system safely be operated after the breakdown? “

### **Geometry and boundary conditions**

The basic geometry of the system is simplified and shown in the following figure (viewed from the top):



### **Coordinate system**

The zero position is set at the outer lower left corner of the casing as shown in the figure. Zero z-position is at the bottom of the box. Gravity is pointing in negative z-direction.



### Component 1 – Housing

Material: aluminium

### Component 2 – Water Cooling System

#### Pipes:

Material: copper

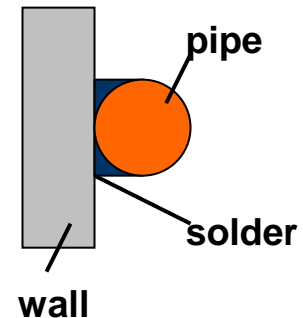
The pipes are soldered to the walls inside the box as shown in the following figure (z-x-plane):

#### Cooling fluid:

Material: water at 1 bar

Flow rate: 1 l/min

Fluid inlet temperature: 35 °C



### Component 3 – Ventilation Fan

Dimensions:

diameter : 80 mm

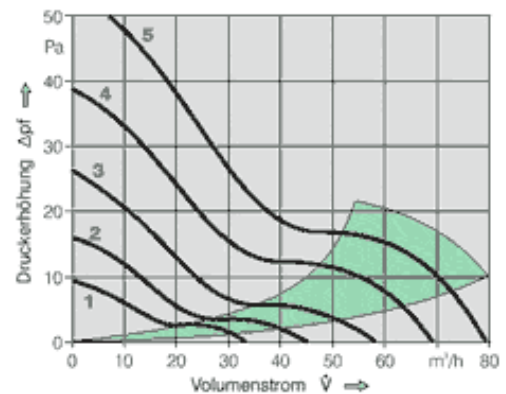
mounted on the bottom plate

Operation conditions:

fan speed: 2050 rpm

direction of flow: positive x-direction

Pressure raise (“Druckerhöhung”) as function of the volume flow rate (“Volumenstrom”) as depicted for line 2.



### Component 4 – Ventilation Fan

The same as Component 3 except that the direction of flow is negative x-direction.

### Component 5 - Electrolytic capacitor

Material: Aluminium / Heat release: 0.5 W

### Component 6 – two identical boards

Material: FR4 / Heat release: 5 W each

### Component 7 – board

Material: FR4 / Heat release: 7.5 W

### Component 8 – two identical stacked boards, with connector board

Material: FR4 / Heat release: 8 W each

### Component 9 – power supply unit with voltage convertor

Material: Copper / Heat release: 22 W

### Component 10 – ambiance

Air at 1 bar with a constant temperature of 33 °C is surrounding the box.

The ambiance is enclosed by walls at 33 °C with emissivity of  $\epsilon = 1$ .

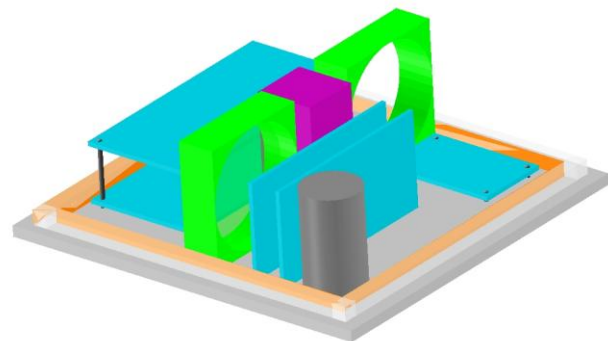
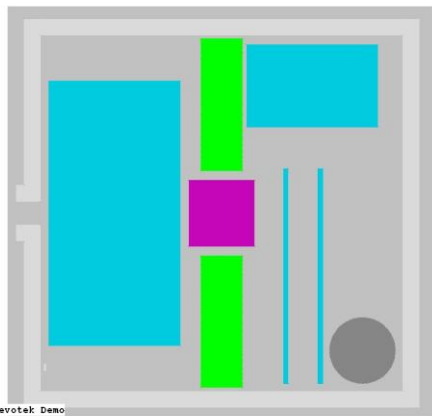


### Material properties

Name	density [kg/m <sup>3</sup> ]	heat capacity [J/kgK]	thermal conductivity [W/mK]	emissivity [-]
Copper and Solder	8930	382	399	0.76
Steel	7800	500	15	0.24
FR4	1938	878	17	0.9
Aluminium	2700	888	237	0.2
filling of the capacitor	1300	1250	0.2	-
water	992	4177	0.631	-

### The CFD model

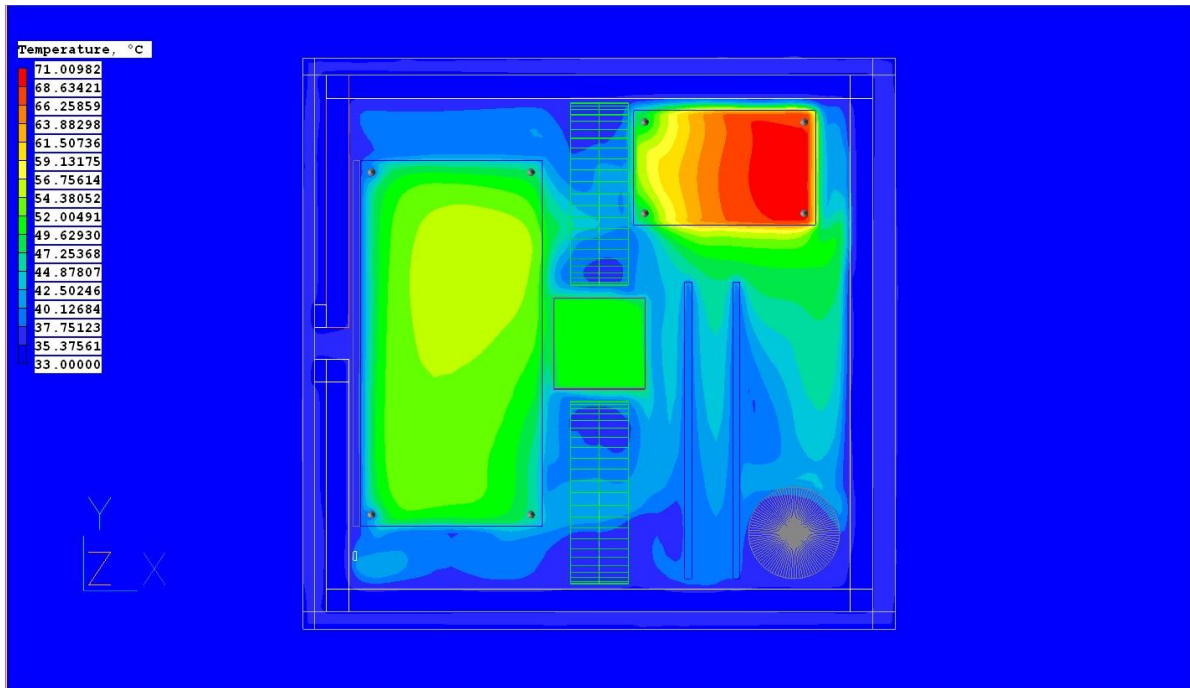
A CFD model was created using objects from the built-in HOTBOX library within PHOENICS using the dimensional and operational data supplied by the client, as above.



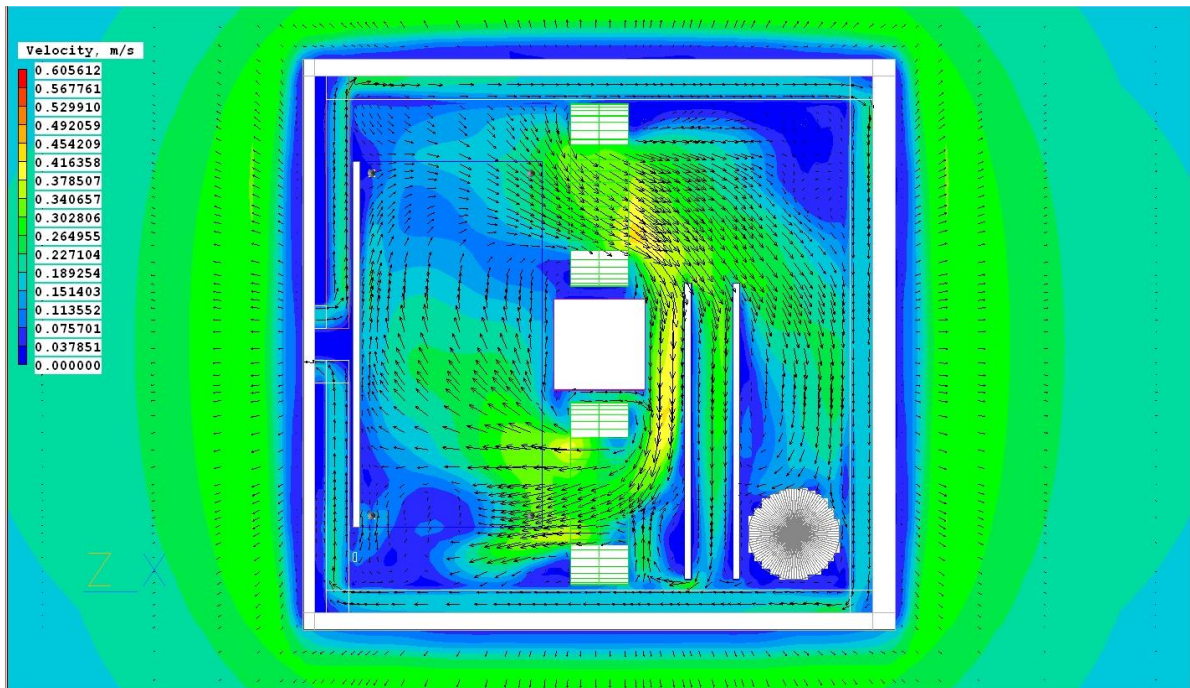
A relatively coarse mesh of 119 x 141 x 76 was applied. Given the nature of the geometric features, PARSOL, was not required. The IMMERSOL radiation model was activated, with the LEVEL turbulence model selected, and a transient (time-dependent) operation of 10 time steps covering a 5-minute period. The run time, on a 3GHz PC was 12.7 hours.

The following images show velocity and temperature results after 300 seconds, in plan and cross-sectional views through the domain. The geometry is shown in wire-frame.

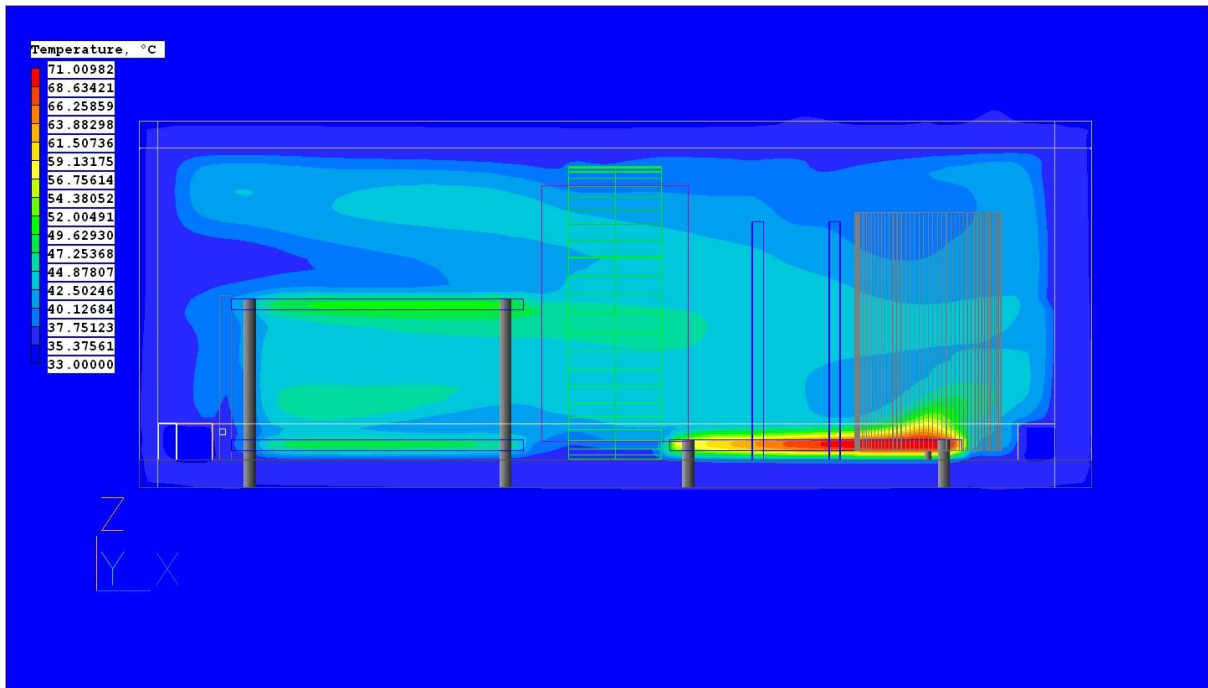
An animation of velocity can be found by clicking [here](#).  
 An animation of temperature can be found by clicking [here](#).



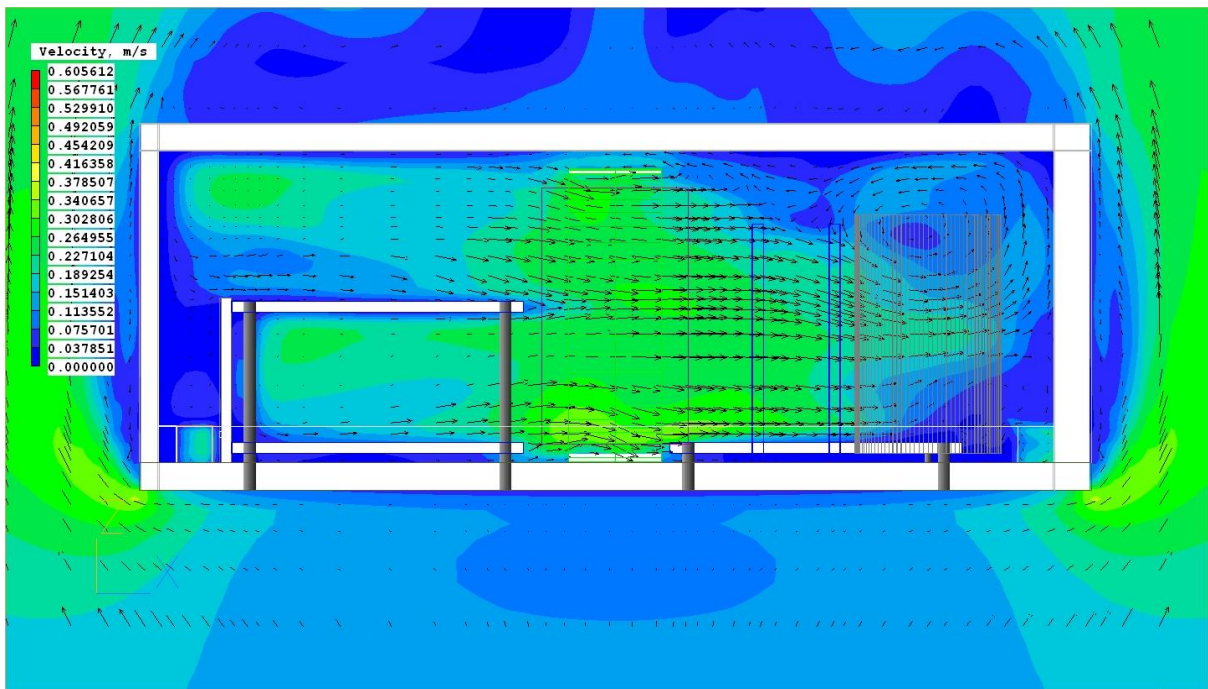
Temperature High Spot XY



Velocity High Spot XY

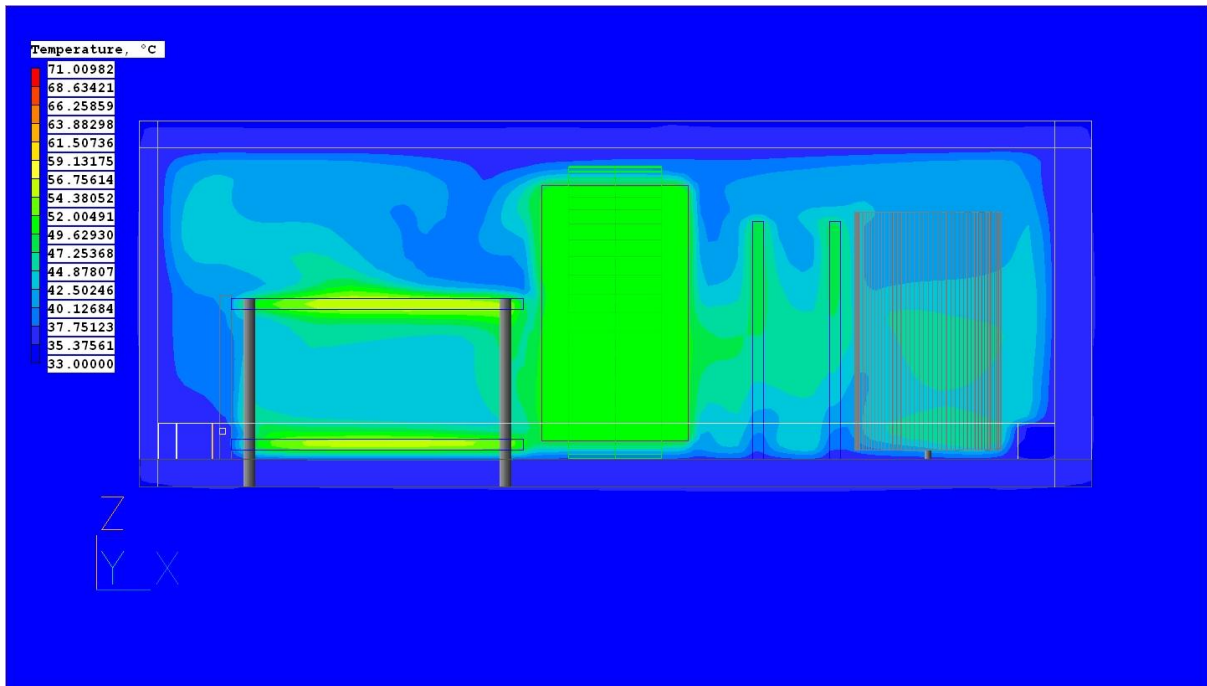


Temperature High Spot XZ

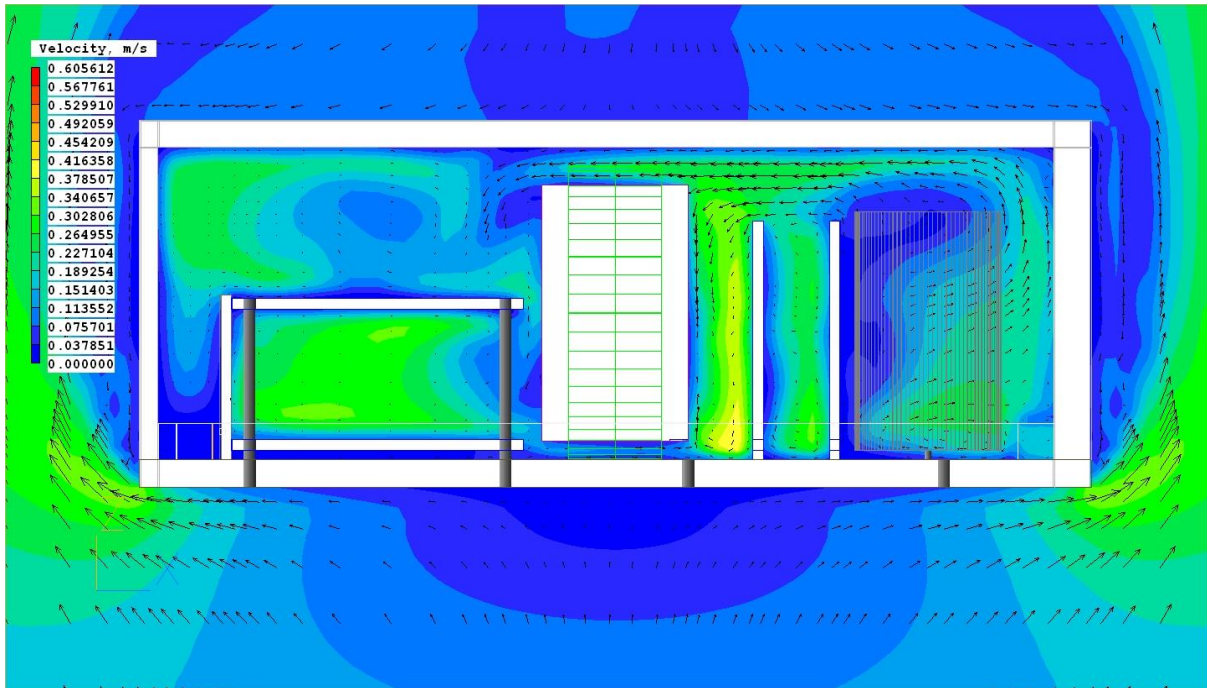


Velocity High Spot XZ





Temperature Centreline XZ



Temperature Centreline XZ